





100V PNP LED DRIVING TRANSISTOR IN SOT223

Features

- BV_{CEO} > -100V
- Maximum continuous current $I_C = -1A$
- $h_{FE} > 100 @ I_C = -150 mA, V_{CE} = -0.2 V$
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT223
- Case material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.112 grams (Approximate)

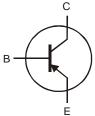
Applications

LED TV backlight

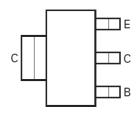




Top View



Device Symbol



Top View Pin-Out

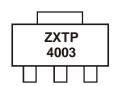
Ordering Information

Ī	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	ZXTP4003GTA	ZXTP4003	7	12	1,000

Notes:

- 1. No purposefully added lead.
- 2. "Green" devices, Halogen and Antimony Free, Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

Marking Information



ZXTP4003 = Product type Marking Code

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Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-100	V
Collector-Emitter Voltage	V _{CEO}	-100	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	lc	-1	А
Peak Pulse Current (Note 4)	I _{CM}	-3	Α
Base Current	Ι _Β	-500	mA

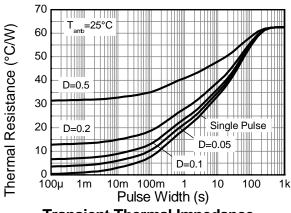
Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _D	2	W
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance, Junction to Leads (Note 5)	R _{θJL}	28.75	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

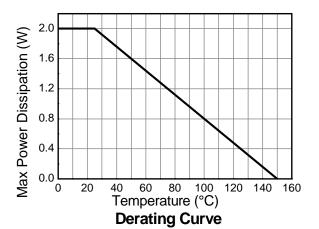
Notes:

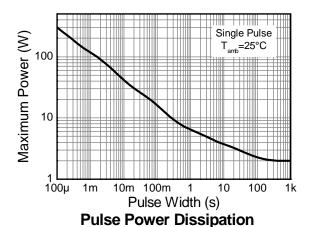
- 3. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
- Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
- 5. Thermal resistance from junction to solder-point (on the exposed collector pad).

Thermal Characteristics and Derating Information



Transient Thermal Impedance





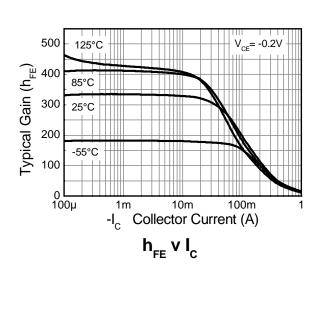


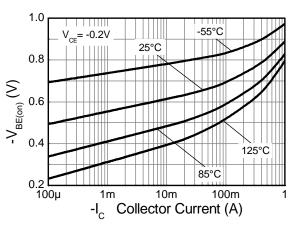
Electrical Characteristics @TA = 25°C unless otherwise specified

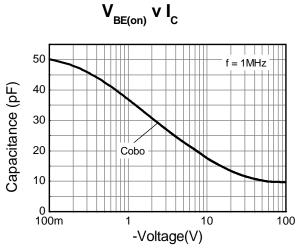
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 6)	BV_CEO	-100	-170	-	V	$I_C = -10 \text{mA}$
Collector Cut-off Current	I _{CBO}	-	-	-50	nA	V _{CB} = -100V
Emitter Cut-off Current	I _{EBO}	-	-	-50	nA	$V_{EB} = -7V$
Static Forward Current Transfer Ratio (Note 6)	hee	60	133	-	_	$I_C = -85 \text{mA}, V_{CE} = -0.15 \text{V}$
Static Forward Current Transfer Ratio (Note 0)	h _{FE}	100	112	-		$I_C = -150 \text{mA}, V_{CE} = -0.2 \text{V}$
Base-Emitter Turn-On Voltage (Note 6)	$V_{BE(on)}$	-	-0.71	-0.95	V	$I_C = -150 \text{mA}, V_{CE} = -0.2 \text{V}$
Delay Time	$t_{(d)}$	-	378	-	ns	
Rise Time	t _(r)	-	388	-	ns	$V_{CC} = -80V, I_{C} = -150mA,$
Storage Time	t _(s)	-	1348	-	ns	$-I_{B2} = 1.5$ mA, $V_{CE(ON)} = -0.2$ V
Fall Time	t _(f)	-	382	-	ns	
Storage Time	t _(s)	-	75	-	ns	$V_{CC} = -80V, I_{C} = -150mA,$
Fall Time	t _(f)	-	363	-	ns	$-I_{B2} = 1.5 \text{mA}, V_{CE(ON)} = -4 \text{V}$

Notes: 6. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$

Electrical Characteristics @TA = 25°C unless otherwise specified



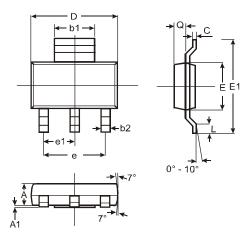




Capacitance v Voltage

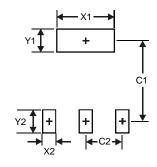


Package Outline Dimensions



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b1	2.90	3.10	3.00		
b2	0.60	0.80	0.70		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	_	_	4.60		
e1	_	_	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3





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